

ABSTRACT

Disclosed is a temporary protective film for producing a semiconductor device, the temporary protective film being used for temporarily protecting a surface of a semiconductor substrate that is opposite to a surface on which a semiconductor element is mounted. The temporary protective film includes an adhesive layer containing acrylic rubber. When the temporary protective film is attached to a copper alloy plate at 25°C so that the adhesive layer is in contact with the copper alloy plate, and the obtained laminate is sequentially heated at 180°C for 60 minutes and at 200°C for 60 minutes, a 90-degree peeling strength of the temporary protective film against the copper alloy plate is 5 N/m or more at 25°C before heating the laminate and 150 N/m or less at 50°C after heating the laminate.

Fig. 1